

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hiroyuki Kousaka	01/05/2009
Hitoshi Iida	01/05/2009
Noritsugu Umehara	01/05/2009
RECEIVING PARTY DATA	
Name:	National University Corporation Nagoya University
Street Address:	1, Furo-cho, Chikusa-ku
City:	Nagoya-shi, Aichi
State/Country:	JAPAN
Postal Code:	4648601
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12374365
CORRESPONDENCE DATA	
Fax Number:	(520)770-2237
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	520-770-8700
Email:	avanicek@quarles.com
Correspondent Name:	Gavin Milczarek-Desai/QUARLES & BRADY
Address Line 1:	ONE SOUTH CHURCH AVENUE, SUITE 1700
Address Line 4:	TUCSON, ARIZONA 85701-1621
ATTORNEY DOCKET NUMBER:	116566.00009
NAME OF SUBMITTER:	Gavin J. Milczarek-Desai
Total Attachments: 3 source=Patent_Assignment_12374365#page1.tif source=Patent_Assignment_12374365#page2.tif	

CH \$40.00 12374365

500757515

PATENT
REEL: 022125 FRAME: 0353

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, Hiroyuki Kousaka, (Assignor) do hereby assign and transfer unto National University Corporation Nagoya University, a non-profit corporation (hereinafter "Assignee"), having its principal offices at 1, Furo-cho, Chikusa-ku, Nagoya-shi, Aichi, 4648601, Japan, and unto its successors, assigns and legal representatives, the entire right, title and interest to a certain invention entitled "Plasma Processing Device, Plasma Processing Method, and Plasma Surface Processing Method" described and illustrated in an application for Letters Patent of the United States of America, Application Serial No. 12/374,365, filed on January 19, 2009, together with the entire right, title and interest in and to said application, and in and to Letters Patent which may be issued upon said application, and in any division, extension, continuation or reissue thereof, said Assignee bearing all patent application expenses, including attorney fees.

I also hereby assign and transfer unto Assignee, the entire right, title and interest in and to said inventions and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of said inventions and said applications for Letters Patent in foreign countries; I further authorize Assignee, to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of said application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to Assignee, for the sole use and benefit of Assignee, its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

I agree that, when requested, I will, without charge to Assignee, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and/or maintaining patents for said invention in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

I covenant with Assignee, its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

Hiroyuki Kousaka
Hiroyuki Kousaka

Jan. 5. 2009
Date

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, Hitoshi Iida, (Assignor) do hereby assign and transfer unto National University Corporation Nagoya University, a non-profit corporation (hereinafter "Assignee"), having its principal offices at 1, Furo-cho, Chikusa-ku, Nagoya-shi, Aichi, 4648601, Japan, and unto its successors, assigns and legal representatives, the entire right, title and interest to a certain invention entitled "Plasma Processing Device, Plasma Processing Method, and Plasma Surface Processing Method" described and illustrated in an application for Letters Patent of the United States of America, Application Serial No. 12/374,365, filed on January 19, 2009, together with the entire right, title and interest in and to said application, and in and to Letters Patent which may be issued upon said application, and in any division, extension, continuation or reissue thereof, said Assignee bearing all patent application expenses, including attorney fees.

I also hereby assign and transfer unto Assignee, the entire right, title and interest in and to said inventions and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of said inventions and said applications for Letters Patent in foreign countries; I further authorize Assignee, to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of said application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to Assignee, for the sole use and benefit of Assignee, its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

I agree that, when requested, I will, without charge to Assignee, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and/or maintaining patents for said invention in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

I covenant with Assignee, its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.

Hitoshi Iida
Hitoshi Iida

Jan. 5, 2009
Date

ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, Noritsugu Umehara, (Assignor) do hereby assign and transfer unto National University Corporation Nagoya University, a non-profit corporation (hereinafter "Assignee"), having its principal offices at 1, Furo-cho, Chikusa-ku, Nagoya-shi, Aichi, 4648601, Japan, and unto its successors, assigns and legal representatives, the entire right, title and interest to a certain invention entitled "Plasma Processing Device, Plasma Processing Method, and Plasma Surface Processing Method" described and illustrated in an application for Letters Patent of the United States of America, Application Serial No. 12/374,365, filed on January 19, 2009, together with the entire right, title and interest in and to said application, and in and to Letters Patent which may be issued upon said application, and in any division, extension, continuation or reissue thereof, said Assignee bearing all patent application expenses, including attorney fees.

I also hereby assign and transfer unto Assignee, the entire right, title and interest in and to said inventions and in and to applications for Letters Patent therefor in all countries foreign to the United States of America, including all rights under any and all international conventions and treaties in respect of said inventions and said applications for Letters Patent in foreign countries; I further authorize Assignee, to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of said application for Letters Patent of the United States of America under the provisions of any and all international conventions and treaties.

I hereby authorize and request the Commissioner of Patents of the United States of America to issue Letters Patent upon the aforesaid application, division, extension, continuation or reissue, to Assignee, for the sole use and benefit of Assignee, its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted, the same as they would have been held and enjoyed by me had this assignment not been made, and I hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to Assignee.

I agree that, when requested, I will, without charge to Assignee, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable or convenient for securing and/or maintaining patents for said invention in any and all countries and for vesting title thereto in said Assignee, its successors, assigns and legal representatives or nominees.

I covenant with Assignee, its successors, assigns and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license or other encumbrance.


Noritsugu Umehara

Jan. 5. 2009
Date